



N-CHANNEL ENHANCEMENT MODE MOSFET WITH SCHOTTKY DIODE

Product Summary

V _{(BR)DSS}	R _{DS(on)}	I _D max T _A = +25°C
30V	15mΩ @ V _{GS} = 10V	10.7A
307	18.5mΩ @ V _{GS} = 4.5V	9.6A

Description

This new generation MOSFET is designed to minimize the on-state resistance (R_{DS(on)}) yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

Applications

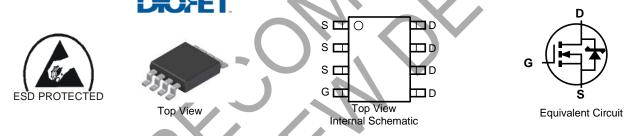
- **DC-DC Converters**
- Power Management Functions

Features

- DIOFET Utilizes a Unique Patented Process to Monolithically Integrate a MOSFET and a Schottky in a Single Die to Deliver:
 - Low RDS(ON)-Minimizes Conduction Losses
 - Low V_{SD}—Reduces Losses due to Body Diode Conduction
 - Low Qrr-Lower Qrr of the Integrated Schottky Reduces Body Diode Switching Losses
 - Low Gate Capacitance (Qg/Qgs) Ratio-Reduces Risk of SHOOT-THROUGH or Cross Conduction Currents at High Frequencies
 - Avalanche Rugged-IAR and EAR Rated
- **ESD** Protected
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
 - Moisture Sensitivity: Level 1 per J-STD-020
 - Terminal Connections: See Diagram Below
- Weight: 0.072 grams (approximate)



Ordering Information (Note 4)

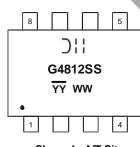
Part Number	Case	Packaging
DMG4812SSS-13	SO-8	2500/Tape & Reel

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.

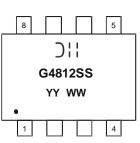
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free
 - 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 - For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information

Notes:



Chengdu A/T Site



Shanghai A/T Site

);; = Manufacturer's Marking G4812SS = Product Type Marking Code YYWW = Date Code Marking YY or \overline{YY} = Year (ex: 13 = 2013) WW = Week (01 - 53) YY = Date Code Marking for SAT (Shanghai Assembly/ Test site) YY = Date Code Marking for CAT (Chengdu Assembly/ Test site)



Maximum Ratings ($@T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V _{DSS}	30	V
Gate-Source Voltage			V _{GSS}	±12	V
Continuous Drain Current (Note 5) V_{GS} = 10V	Steady State	T _A = +25°C T _A = +85°C	Ι _D	8 6.4	А
Continuous Drain Current (Note 6) $V_{GS} = 10V$	$t \leq 10 \; \text{sec}$	T _A = +25°C T _A = +85°C	ID	10.7 8.6	А
Continuous Drain Current (Note 6) V_{GS} = 4.5V	$t \leq 10 \; \text{sec}$	T _A = +25°C T _A = +85°C	ID	9.6 7.7	А
Pulsed Drain Current (Note 7)			I _{DM}	45	А
Avalanche Current (Notes 7 & 8)			I _{AR}	13	А
Repetitive Avalanche Energy (Notes 7 & 8) L = 0.3mH			E _{AR}	25.4	mJ

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	PD	1.54	W
Thermal Resistance, Junction to Ambient $@T_A = +25^{\circ}C$ (Note 5)	R _{0JA}	81	°C/W
Power Dissipation (Note 6)	PD	2.8	W
Thermal Resistance, Junction to Ambient $@T_A = +25^{\circ}C$ (Note 6)	Reja	45	°C/W
Operating and Storage Temperature Range	TJ, T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

		4				
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 9)						
Drain-Source Breakdown Voltage	BV _{DSS}	30		_	V	$V_{GS} = 0V, I_D = 1mA$
Zero Gate Voltage Drain Current	IDSS	—	_	150	μA	$V_{DS} = 30V, V_{GS} = 0V$
Gate-Source Leakage	I _{GSS}	—	—	±100	nA	$V_{GS} = \pm 12V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 9)						
Gate Threshold Voltage	V _{GS(th)}	1.0	_	2.3	V	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$
Static Drain-Source On-Resistance		-	11	15	mΩ	$V_{GS} = 10V, I_D = 10.7A$
Static Drain-Source On-resistance	RDS (ON)	_	16.5	18.5	11152	$V_{GS} = 4.5V, I_D = 9.6A$
Forward Transfer Admittance	Y _{fs}	_	20		s	$V_{DS} = 5V, I_D = 10.7A$
Diode Forward Voltage	VsD		0.36	0.5	V	$V_{GS} = 0V, I_{S} = 1A$
Maximum Body-Diode + Schottky Continuous Current	ls	—	—	5	А	—
DYNAMIC CHARACTERISTICS (Note 10)						
Input Capacitance	Ciss	—	1849		pF	
Output Capacitance	Coss	_	158	—	pF	V _{DS} =15V, V _{GS} = 0V, f = 1.0MHz
Reverse Transfer Capacitance	Crss	—	123	—	pF	
Gate Resistance	Rg	0.54	2.0	4.0	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1MHz$
Total Gate Charge V _{GS} = 4.5V	Qg	—	18.5		nC	
Total Gate Charge V _{GS} = 10V	Qg	—	43	—	nC	V _{DS} = 15V, V _{GS} = 10V,
Gate-Source Charge	Q _{gs}	_	4.7	—	nC	I _D = 9.6A
Gate-Drain Charge	Q _{gd}	—	4.0	—	nC	
Turn-On Delay Time	t _{D(on)}		6.62	_	ns	
Turn-On Rise Time	tr	_	8.73	_	ns	V _{GS} = 10V, V _{DS} = 15V,
Turn-Off Delay Time	t _{D(off)}		36.41	_	ns	$R_G = 3\Omega$, $R_L = 15\Omega$, $I_D = 1A$
Turn-Off Fall Time	t _f		4.69	—	ns	

Notes:

5. Device mounted on FR-4 PCB with minimum recommended pad layout. The value in any given application depends on the user's specific board design. 6. Device mounted on $1^* \times 1^*$ FR-4 PCB with high coverage 1 oz. Copper, single sided, device is measured at t \leq 10 sec.

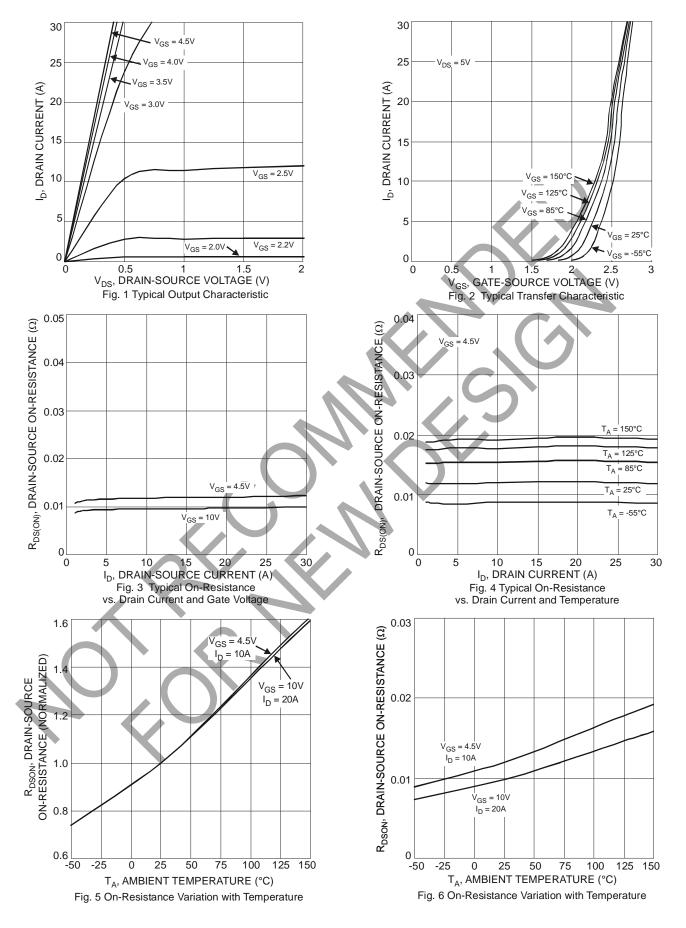
7. Repetitive rating, pulse width limited by junction temperature.

8. I_{AR} and E_{AR} rating are based on low frequency and duty cycles to keep $T_J = +25^{\circ}C$ 9. Short duration pulse test used to minimize self-heating effect.

10. Guaranteed by design. Not subject to production testing.

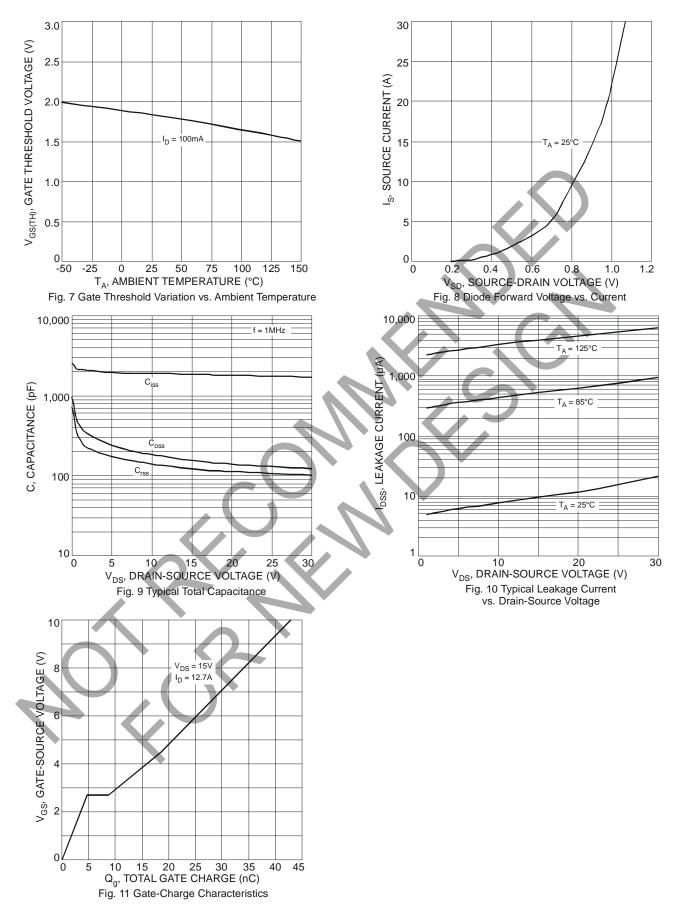


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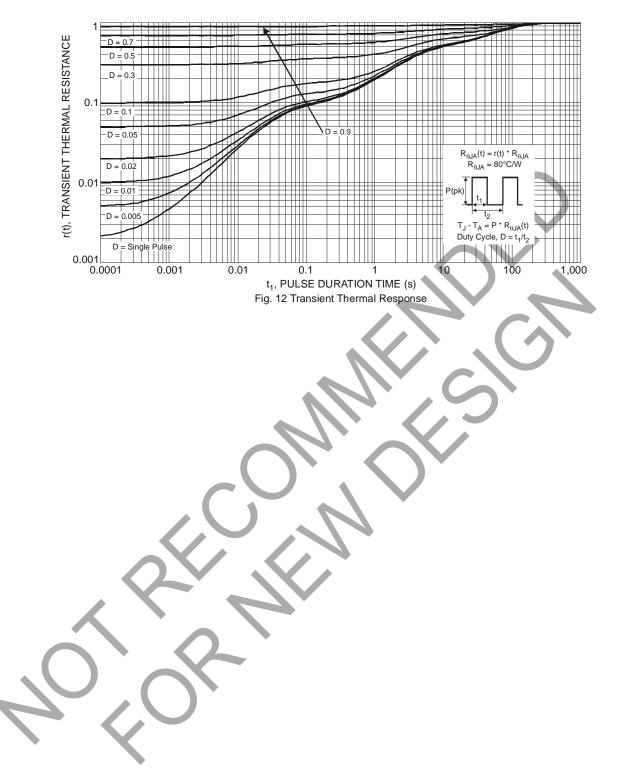




DMG4812SSS



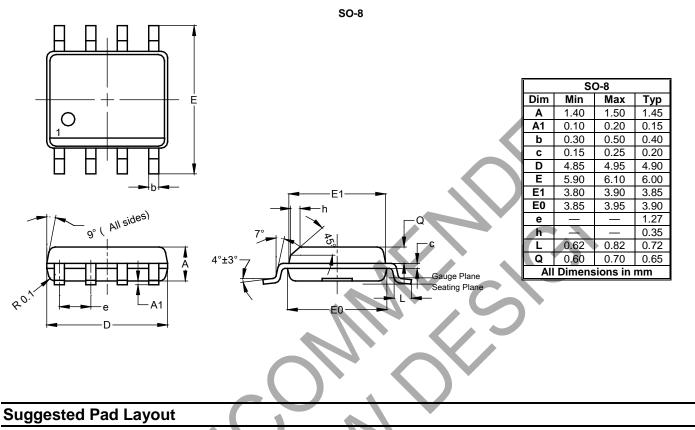




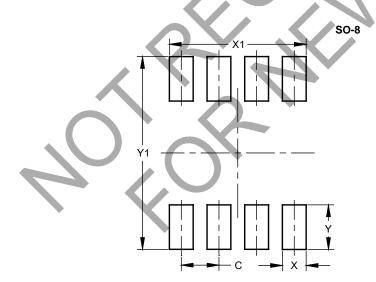


Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version



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Dimensions	Value (in mm)
C	1.27
Х	0.802
X1	4.612
Y	1.505
Y1	6.50



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